



Material Content Data Sheet



Sales Product Name		TLF4949SJ		Issued		27. September 2017		
MA#		MA001001404						
Package		PG-DSO-8-44		Weight*		82.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.577	0.70	0.70	6987	6987
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8684	
wire	non noble metal	copper	7440-50-8	29.121	35.26	36.18	352599	361826
	non noble metal	copper	7440-50-8	0.083	0.10	0.10	1002	1002
	organic material	carbon black	1333-86-4	0.101	0.12		1219	
encapsulation	plastics	epoxy resin	-	4.630	5.61		56057	
	inorganic material	silicondioxide	60676-86-0	45.593	55.20	60.93	552041	609317
leadfinish	non noble metal	tin	7440-31-5	0.814	0.99	0.99	9854	9854
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7873	7873
glue	plastics	acrylic resin	-	0.057	0.07		691	
	noble metal	silver	7440-22-4	0.202	0.24	0.31	2450	3141
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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